# High Frequency Ceramic Solutions

**Preliminary** 

# 896 MHz Balun/Matching Network for T.I. Chipset CC11XX P/N 0896BM15A0001 Detail Specification: 10/24/08 Page 1 of 2

#### **General Specifications**

| outer an opposition to          |                                    |  |
|---------------------------------|------------------------------------|--|
| Part Number                     | 0896BM15A0001                      |  |
| Frequency (MHz)                 | 863 - 928 MHz                      |  |
| Unbalanced Impedance            | 50 Ω                               |  |
| Differential Balanced Impedance | Conj. match to T.I. CC11XX Chipset |  |
| Insertion Loss                  | 1.5 dB max.                        |  |
| Return Loss                     | 9.5 dB min.                        |  |
|                                 | 25 @ 1726 - 1856MHz                |  |
| Attenuation (min.)              | 35 min.@ 2589 - 2784MHz            |  |
|                                 | 35 min.@ 3452 - 3712MHz            |  |
|                                 | 35 min.@ 4315 - 4640MHz            |  |

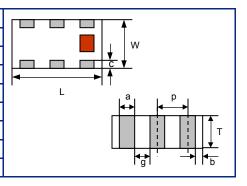
| Phase Difference      | 180° ± 10           |
|-----------------------|---------------------|
| Amplitude Difference  | 1.5 dB max.         |
| Operating Temperature | -40 to +85°C        |
| Power Rating          | 1W max.             |
| Storage               | +5 to +35°C,        |
| Conditions            | Humidity 45 - 75%RH |
| Storage Period        | 12 mos. Max         |
| Reel quantity         | 4000 pcs            |

## **Terminal Configuration**

| No. | Function        |  |
|-----|-----------------|--|
| 1   | Unbalanced Port |  |
| 2   | GND             |  |
| 3   | Balanced Port   |  |
| 4   | Balanced Port   |  |
| 5   | GND             |  |
| 6   | GND             |  |
|     | 3 2 1           |  |
| ١   |                 |  |

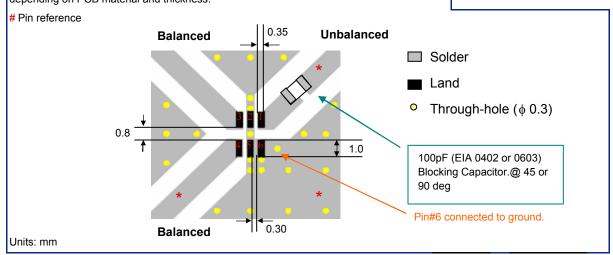
#### **Mechanical Dimensions**

|   | ln              | mm              |
|---|-----------------|-----------------|
| L | 0.079 ± 0.004   | 2.00 ± 0.10     |
| W | 0.049 ± 0.004   | 1.25 ± 0.10     |
| Т | 0.028 ± 0.004   | 0.70 ± 0.10     |
| а | 0.012 ± 0.004   | 0.30 ± 0.10     |
| b | 0.008 ± 0.004   | 0.20 ± 0.10     |
| С | 0.012 +.004/008 | 0.30 +0.1/-0.20 |
| g | 0.014 ± 0.004   | 0.35 ± 0.10     |
| р | 0.026 ± 0.002   | 0.65 ± 0.05     |



## **Mounting Considerations**

\* Line width should be designed to match 50  $\Omega$  characteristic impedance, depending on PCB material and thickness.



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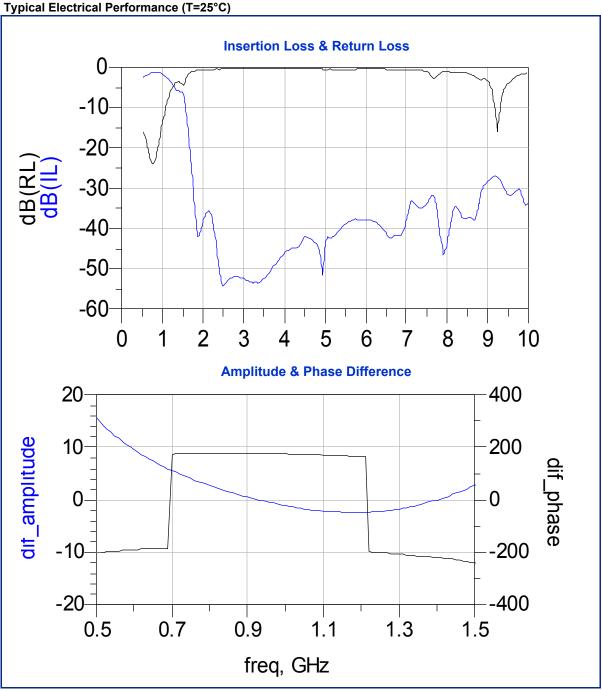
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896 MHz Balun/Matching Network for T.I. Chipset CC11XX

P/N 0896BM15A0001

Detail Specification: 10/24/08 Page 2 of 2



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